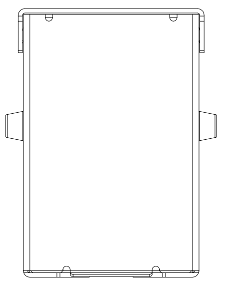
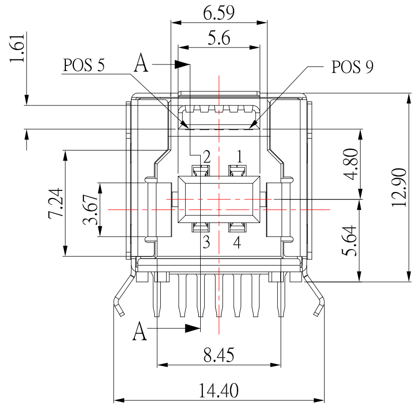
# SUB-110H-30x-S277

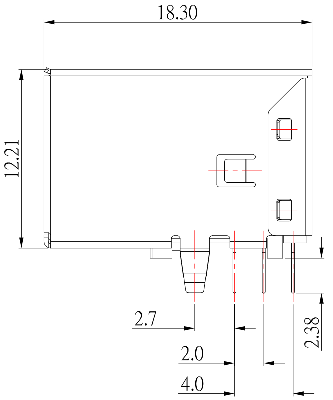
**RoHS Compliant**

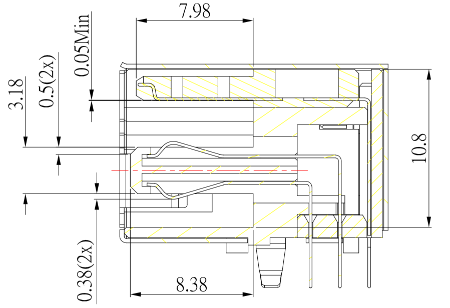
鍍層厚度 :

| |
|---|
| Blank : 1u" |
| 2 : 15u" |
| 3 : 30u" |

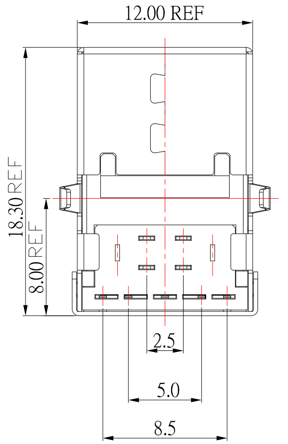


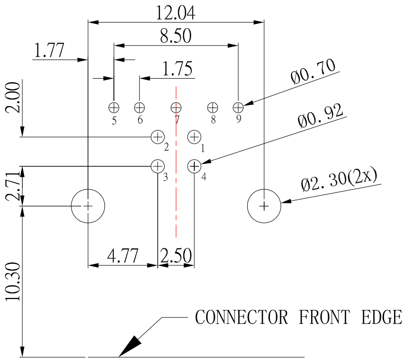






| Pin NUMBER | SIGNAL NAME |
|---|---|
| 1 | VBUS |
| 2 | D- |
| 3 | D+ |
| 4 | GND |
| 5 | StdB_SSTX- |
| 6 | StdB_SSTX+ |
| 7 | GND_DRAIN |
| 8 | StdB_SSRX- |
| 9 | StdB_SSRX+ |
| Shell | Shield |





RECOMMENDED PCB LAYOUT

NOTE:

1.MATERIAL:

1.1 Housing: LCP,(UL94V-0)

1.2 Contact: 1-4 Pin: PHOSPHOR BRONZE
5-9 Pin: BRASS

1.3 Shell: BRASS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Current Rate:1.5 A

3.2 insulator Resistance:1000MΩ Min

3.3 Dielectric Strength: 500V AC

3.4 Contact Resistance: 30mΩ Max

3.5 Operation Temperature: 0˚C ~ +50˚C

3.6 Insertion Force: 3.57 Kg Max

3.7 Extraction Force: 1.02 Kg Min

| ITEM NO. | DESCRIPTION | DRAWN | DATE |
|---|---|---|---|
| 1 | 更新SPEC及材質 | Jack | 070215 |

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED :

| | |
|---|---|
| Up to 5 | ±0.2 |
| Above 5 ~ 15 | ±0.3 |
| Above 15 ~ 30 | ±0.4 |
| Above 30 ~ 50 | ±0.5 |
| Angle | ±0.3˚ |

3RD. ANGEL'S

| UNITS | MM |
|---|---|

| | | | | | | |
|---|---|---|---|---|---|---|
| DRAWN BY: Jack Lu | DATE 07/02/15 | MAT'L | | TITLE | CONNECTOR | |
| CHECKED BY: Jacky Chen | DATE 07/02/15 | FINISH | | MODLE | USB CONNECTOR | |
| APPROVED BY: Tony Kao | DATE 07/02/15 | SCALE | 1 : 1 | DWG NO. | SUB-110H-30x-S277 | SIZE A4 |
| | | SHEET NO. | 1 of 1 | PART NO. | SUB-110H-30x-S277 | VER A1 |